

Silicon PIN Photodiode

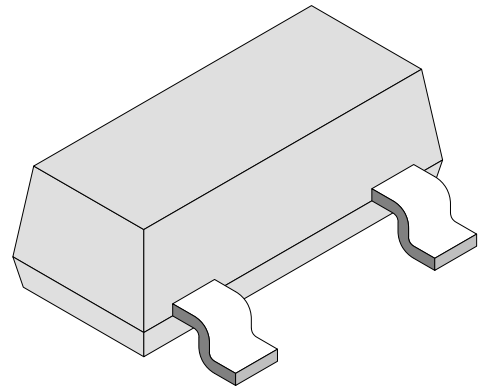
Description

TEMD2100 is a high speed silicon PIN photodiode in a miniature SOT-23 package for surface mounting on printed boards. Its flat package provides an extra wide viewing angle.

Due to its waterclear epoxy the device is sensitive to visible and near infrared radiation.

Features

- Extra fast response times
- Radiant sensitive area $A=0.25\text{mm}^2$
- Standard SOT-23 package
- Especially for surface mounting on printed board
- Extra wide angle of half sensitivity $\phi = \pm 75^\circ$
- Small mechanical tolerances



94 8550

Applications

Wide band detector in SMD technique

Absolute Maximum Ratings

$T_{\text{amb}} = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		V_R	60	V
Power Dissipation	$T_{\text{amb}} \leq 25^\circ\text{C}$	P_V	75	mW
Junction Temperature		T_j	100	$^\circ\text{C}$
Storage Temperature Range		T_{stg}	-55...+100	$^\circ\text{C}$
Soldering Temperature	$t \leq 5\text{ s}$	T_{sd}	240	$^\circ\text{C}$
Thermal Resistance Junction/Ambient		R_{thJA}	1000	K/W

Basic Characteristics

$T_{amb} = 25^{\circ}\text{C}$

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	$I_F = 50 \text{ mA}$	V_F		1.0	1.3	V
Breakdown Voltage	$I_R = 100 \text{ }\mu\text{A}, E = 0$	$V_{(BR)}$	60			V
Reverse Dark Current	$V_R = 10 \text{ V}, E = 0$	I_{ro}		1	10	nA
Diode Capacitance	$V_R = 5 \text{ V}, f = 1 \text{ MHz}, E = 0$	C_D		1.8		pF
Reverse Light Current	$E_e = 1 \text{ mW/cm}^2, \lambda = 870 \text{ nm}, V_R = 5 \text{ V}$	I_{ra}	2.0	2.5		μA
	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}, V_R = 5 \text{ V}$	I_{ra}		2.3		μA
Temp. Coefficient of I_{ra}	$V_R = 5 \text{ V}, \lambda = 870 \text{ nm}$	$TK_{I_{ra}}$		0.2		%/K
Absolute Spectral Sensitivity	$V_R = 5 \text{ V}, \lambda = 870 \text{ nm}$	$s(\lambda)$		0.60		A/W
	$V_R = 5 \text{ V}, \lambda = 950 \text{ nm}$	$s(\lambda)$		0.55		A/W
Angle of Half Sensitivity		ϕ		± 75		deg
Wavelength of Peak Sensitivity		λ_p		900		nm
Range of Spectral Bandwidth		$\lambda_{0.5}$		570...1050		nm
Rise Time	$V_R=50\text{V}, R_L=50\Omega, \lambda=850\text{nm}$	t_r		2.5		ns
Fall Time	$V_R=50\text{V}, R_L=50\Omega, \lambda=850\text{nm}$	t_f		2.5		ns

Typical Characteristics ($T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified)

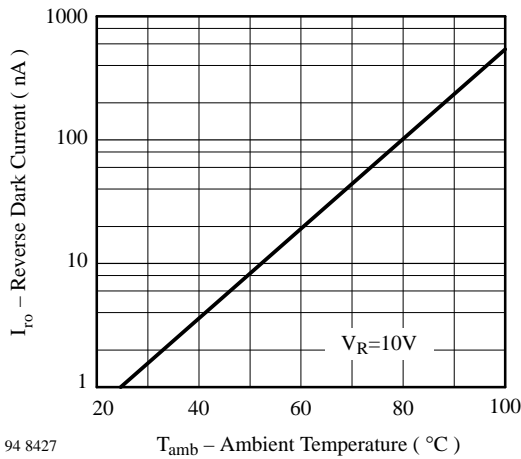


Figure 1. Reverse Dark Current vs. Ambient Temperature

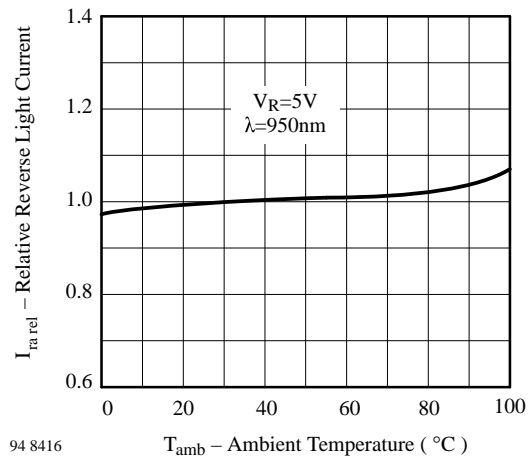


Figure 2. Relative Reverse Light Current vs. Ambient Temperature

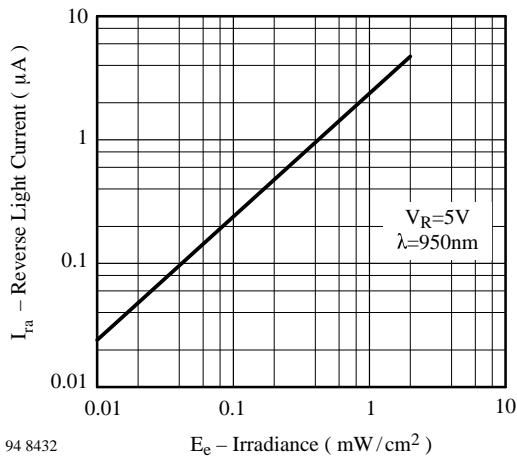


Figure 3. Reverse Light Current vs. Irradiance

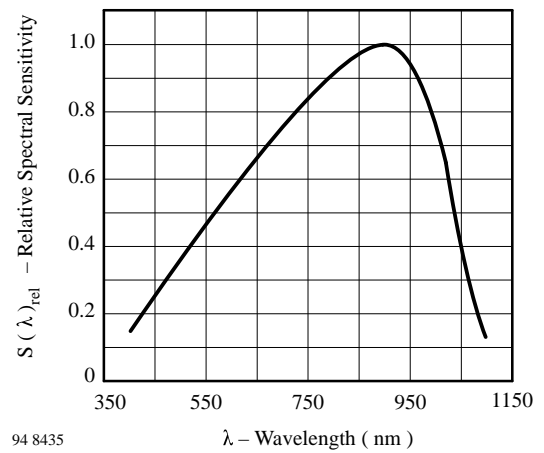


Figure 6. Relative Spectral Sensitivity vs. Wavelength

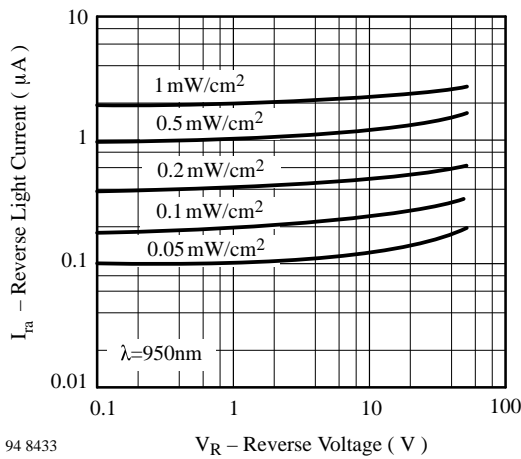


Figure 4. Reverse Light Current vs. Reverse Voltage

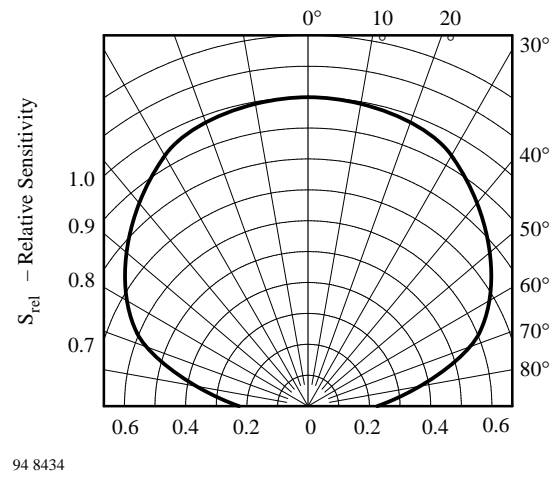


Figure 7. Relative Radiant Sensitivity vs. Angular Displacement

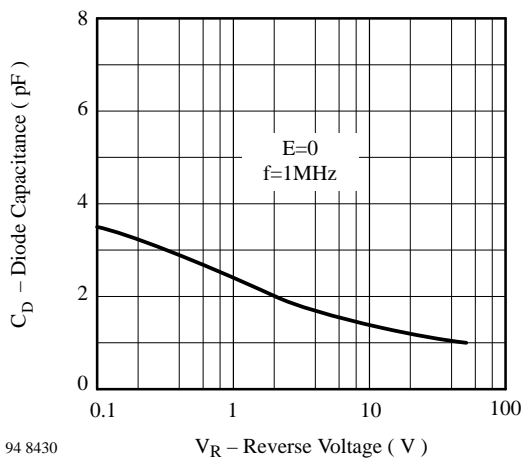
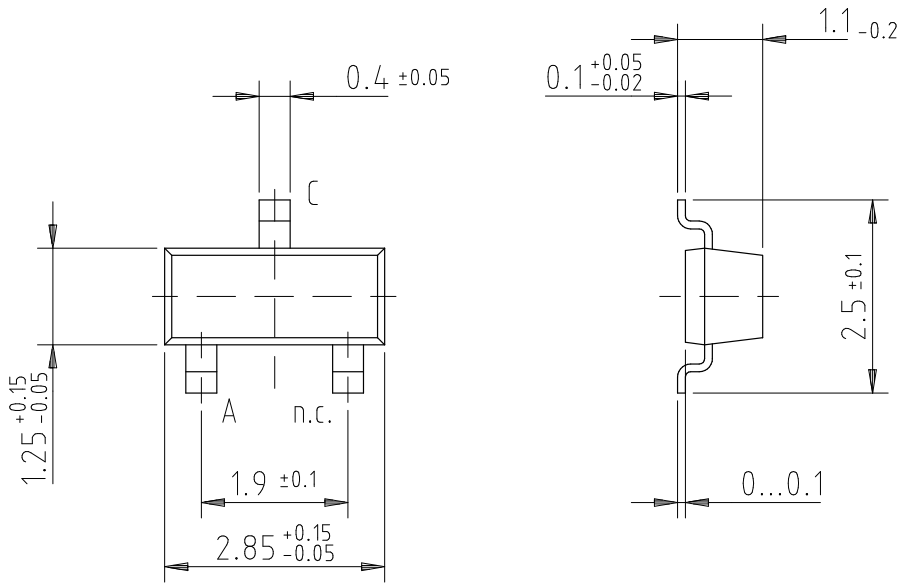
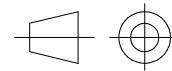


Figure 5. Diode Capacitance vs. Reverse Voltage

Dimensions in mm



96 12177



technical drawings
according to DIN
specifications

Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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